

shaped inductor and a combination of varactors and fixed MIM capacitors. An output buffer is included for measurement purposes. The differential outputs use 50Ω transmission lines to the bond-pads.

III. RESONATOR AND OUTPUT BUFFER

At mm-wave frequencies the required inductors are small and exhibit a reasonably high quality factor (Q). In contrast, quality factor of the capacitive part, i.e. the varactors becomes the dominant factor. The quality factor of a LC tank (Q_{Tank}) is given by $1/Q_{\text{Tank}} = 1/Q_L + 1/Q_C$ where Q_L and Q_C are quality factors of the inductor and capacitors that make up the tank. In case, Q_L is much lower than Q_C , which is generally the case for frequencies up to a few gigahertz, improving Q_L leads to a higher Q_{Tank} . However, at mm-wave frequencies the quality factor of the capacitor (Q_C) is significantly lower than Q_L [3]. Thus, more design effort should be invested in improving Q_C at mm-wave frequencies rather than improving Q_L .

The on-chip integrated inductor is a single turn octagonal shaped coil. It utilizes the thick top metal, to reduce series resistance, thereby increasing the quality factor. The inductor metal width and inner radius are 6μm and 15μm, respectively. The simulated inductance value is 95 pH, with a quality factor of 20 at 40 GHz. The area occupied by the inductor is 60x60 μm.

The tuning of VCO is achieved by combination of accumulation MOS (AMOS) varactors and fixed MIM capacitors (see Fig. 1 (b)). Metal-insulated-metal (MIM) capacitors exhibit high Q-factors (above 20) at mm-wave frequencies due to low intrinsic losses. Thus, using them in series with varactors improves the quality factor, at the expense of reduced tuning range. The $C_{\text{max}}/C_{\text{min}}$ ratio of this setup is 2.1 and Q_C varies between 8.5 and 14.3. The reduced capacitance ratio due to MIM capacitors is not an issue, as the desired frequency tuning range is successfully achieved. The advantage on the other hand is that Q_C improves by approx. 40% as compared to a stand-alone varactor implementation.

In addition, some flexibility is achieved by connecting the lower terminal of the biasing resistors (V_b in Fig. 1(b)) to an external supply instead of grounding them. This provides an extra control voltage to cater parasitics and process variation. If the VCO is tuned single-endedly, common-mode noise can modulate the varactors, and appear as jitter and phase noise at the VCO output. Therefore, differential tuning is adopted for the capacitive part of the LC-tank to alleviate this problem [2].

A common-source differential stage is used as an output buffer, to make on-wafer measurements possible. In order

to avoid loading of the VCO, the buffer is biased independently. This also helps in measuring the power consumption of VCO and buffer separately. The load resistance (silicided poly-silicon based) is 50Ω, to match it with the transmission lines as well as the measurement equipment.

IV. LAYOUT AND TECHNOLOGY

In order to reduce parasitics, layout is done carefully and compactly. The RF signal paths are kept as short as possible and narrow connecting lines are avoided to minimize resistive losses. Ground meshing is used underneath the RF paths. Decoupling capacitors are included for the voltage supplies. The differential outputs use 50Ω transmission lines (TL's) to the bond-pads. These TL's are coplanar waveguide based with lateral ground-plane consisting of all metal layers. The width of the TL is 5μm and spacing from the ground plane is 4.22μm.

The VCO is fabricated in TSMC bulk CMOS 65nm LP (low-power) process having six metallization layers. The process offers MIM capacitors and poly-silicon resistors. The measured f_T of NMOS and PMOS transistors is 140 GHz and 80 GHz, respectively. Due to bond-pad limitation the total chip area is 700 x 400 μm. However, the VCO core only occupies 100 x 100 μm. The chip micrograph is shown in Fig. 2.

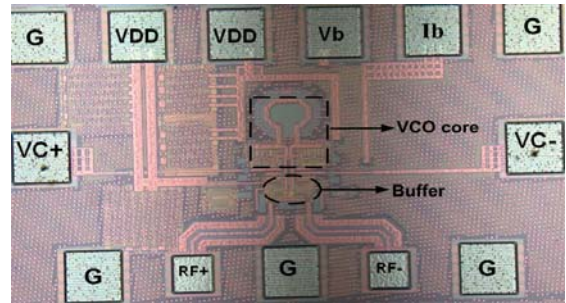


Fig. 2. Chip micrograph

V. MEASUREMENT RESULTS

The VCO was measured on-wafer using a RF differential probe (GSGSG) and a 180° hybrid coupler. An Agilent PSA series spectrum analyzer with phase noise functionality was used for spectral measurements. In order to suppress the noise coming from power supplies, dedicated filters are employed. In addition, common-grounds between the supplies and spectrum analyzer are eliminated. The lighting of the viewing optics is turned-off during measurement [2]. It is noticed that central alignment of the infinity probes (on the bond-pads) and

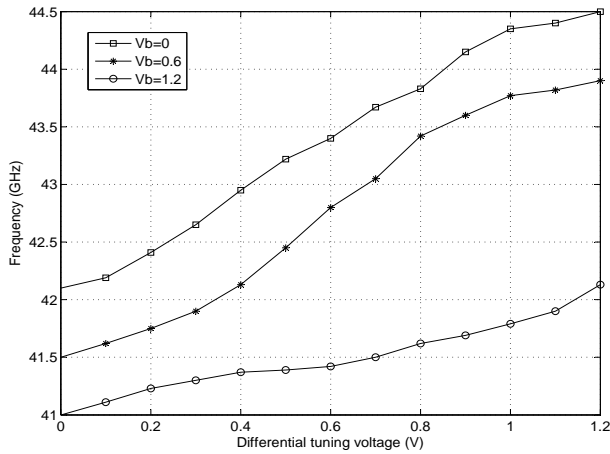


Fig. 3. VCO frequency tuning range

good probe contact yields stable and repeatable measurements.

The frequency tuning range (FTR) of the VCO is shown in Fig. 3, where output oscillation frequency is plotted versus differential tuning voltage for three bias voltages (Vb). The minimum and maximum measured frequencies are 41 GHz and 44.5 GHz (see Fig. 4), respectively, giving a tuning range of 8.1 %.

The VCO and output buffer consume 3mA and 5mA from a 1.2V supply, respectively. The total loss from the wiring cables, connectors and hybrid was measured between 6 and 8 dB over the entire frequency tuning range. After de-embedding this loss, the average differential output power delivered to a 50Ω load is between -2 and -6 dBm.

The measured phase noise of the VCO at 41.2 GHz is shown in Fig. 5. At 100 kHz and 1 MHz offsets, the measured values are -98 and -106 dBc/Hz, respectively. The commonly used FOM for VCOs is defined as

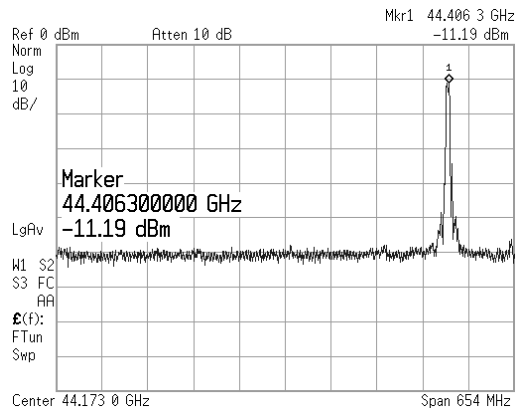


Fig. 4. VCO output spectrum at 44.4 GHz

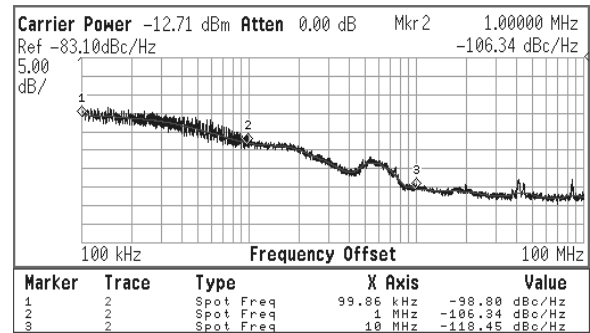


Fig. 5. VCO phase noise for a 41.2 GHz carrier

$FOM = L\{\Delta f\} - 20 \log(f_o/\Delta f) + 10 \log(P_{dc}/1 \text{ mW})$, where $L\{\Delta f\}$ is the measured phase noise at frequency offset Δf from the carrier at f_o , and P_{dc} is the DC power consumption [1]. Using the above expression and measured phase noise at 1-MHz offset, a FOM of -192.7 dBc/Hz is achieved, which is the best reported FOM for VCOs operating above 40 GHz.

As VCO's, at a later stage, become a part of frequency synthesizers in wireless transceivers, their performance variation from die-to-die is undesirable. In order to analyze the spreading of the fabricated VCO, twenty-nine samples were measured. The measurement setup and DC conditions were kept constant in all measurements for a fair comparison. Fig. 6 shows the variation of VCO center frequency for three different bias voltages (Vb). Two corner samples did not work and were probably damaged during wafer fibbing. The measured standard deviation for the three bias voltages (0, 0.6, 1.2V) is 683 MHz, 590 MHz and 629 MHz, respectively.

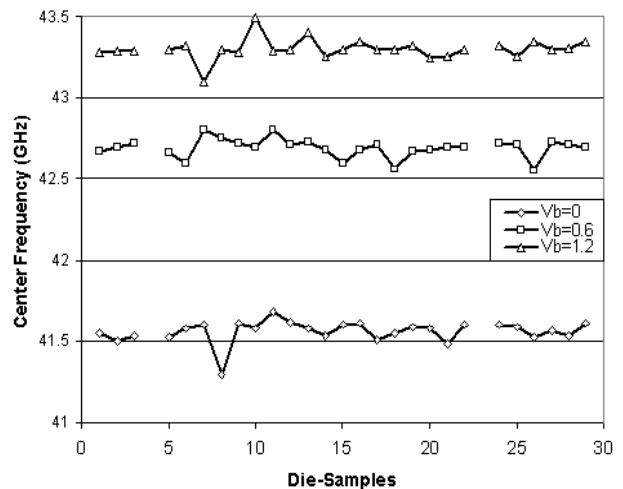


Fig. 6. VCO center frequency variation for different samples

The phase noise and output power variation is also measured. For each sample, the tuning voltage is set in such a way that the oscillation frequency is 41.2 GHz for all samples. Then the phase noise and output power are noted down and shown in Fig.7. The phase noise results show considerable variation, the mean value being -103.75 dBc/Hz with a standard deviation of 1.5 dBc/Hz. The mean output power, after de-embedding loss of the cables etc, is -4.6 dBm and standard deviation is 0.8 dBm.

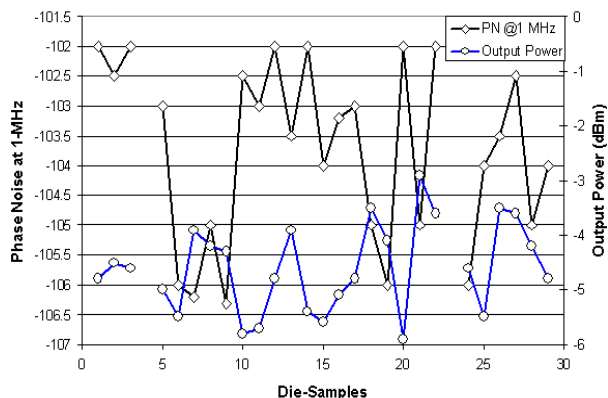


Fig. 7. Phase noise and output power variation

Table I compares, published state-of-the-art VCO's operating at mm-wave frequencies. The presented VCO has the lowest power-consumption (excluding output buffers) while achieving a reasonable frequency tuning range. The phase noise is better than reported SOI implementations in [1], [2].

V. CONCLUSION

A 44.5 GHz complementary LC cross-coupled VCO implemented in a 65nm bulk CMOS LP technology is presented. The use of MIM capacitors to improve Q_c , differential tuning to reduce phase noise and compact layout to minimize parasitics yields good measured results. The VCO has a FTR of 8% and dissipates only 3.6mW. The measured phase noise at 1MHz offset from a 41.2

GHz carrier is -106 dBc/Hz resulting in an excellent FOM of -192.7 dBc/Hz.

TABLE I
COMPARISON WITH PUBLISHED RESULTS

Ref. & Tech.	Freq. (GHz)	P_{dc} (mW)	FTR (%)	PN@1MHz (dBc/Hz)	FOM (dBc/Hz)
[1] 0.13 μ m SOI CMOS	40.7	11.3	15	-89	-170.6
[2] 0.12 μ m CMOS SOI	44	7.5	9.8	-101	-185
[3] 0.13 μ m CMOS	43	7	4.2	-90	-174.2
[4] 0.13 μ m CMOS	59	9.8	10.2	-89	-174.5
[5] 0.18 μ m CMOS	50	4	2	-96	-184
This work 65nm CMOS	44.5	3.6	8.1	-106	-192.7

REFERENCES

- [1] Neric Fong et al., "A Low-Voltage 40-GHz Complementary VCO With 15% Frequency Tuning Range in SOI CMOS Technology," *IEEE JSSC*, vol. 39, pp. 841-846, May 2004.
- [2] Jonghae Kim, J.-O. Plouchart et al., "A 44 GHz Differentially Tuned VCO with 4GHz Tuning Range in 0.12 μ m SOI CMOS," *IEEE ISSCC*, pp 416-417 and 607, Feb., 2005.
- [3] Arnaud P. van der Wel et al., "A Robust 43-GHz VCO in CMOS for OC-768 SONET Applications," *IEEE JSSC*, vol. 39, pp. 1159-1163, July 2004.
- [4] Changhua Cao, Kenneth K.O., "Millimeter-Wave Voltage-Controlled Oscillators in 0.13- μ m CMOS Technology," *IEEE JSSC*, vol. 41, pp. 1297-1304, June 2006.
- [5] Tang-Nian Luo et al., "A 1-V CMOS VCO For 60-GHz Applications," *Asia Pacific Microwave Conf*, Dec. 2005.
- [6] Lin Jia et al., "9.3-10.4-GHz-Band Cross-Coupled Complementary Oscillator With Low Phase-Noise Performance," *IEEE Trans. On Microwave theory and Techniques*, vol.52, pp.1273-1278, April 2004.